

CLAIM AMENDMENTS:

Claims 1-36 (canceled).

Claim 37 (previously presented): A composite laminated substrate for integrated and minimized electronic circuits, comprising:

an inorganic substrate having at least one passive component embedded therein; and

an organic substrate which is laminated to one side of the inorganic substrate and which has circuits for electrical connections between outer input/output ports and the at least one passive component of the inorganic substrate.

Claim 38 (previously presented): The composite laminated substrate according to claim 37, wherein the inorganic substrate is comprised of a material selected from the group consisting of ceramic, silicon and glass.

Claim 39 (currently amended): The composite laminated substrate according to claim 38, wherein the material of the inorganic substrate is ceramic and wherein the at least one passive component is one of a thick film passive component ~~made by a thick film process~~ or a thin film passive component ~~made by a thin film process~~.

Claim 40 (currently amended): The composite laminated substrate according to claim 38, wherein the material of the inorganic substrate is silicon and wherein the at least one passive component is a semiconductor-fabricated passive component made by a semiconductor fabrication process component.

Claim 41 (previously presented): The composite laminated substrate according to claim 37, wherein the at least one passive component is selected from the group consisting of a capacitor, an inductor, a resistor, and any mixture thereof.

Claim 42 (currently amended): The composite laminated substrate according to claim 37, wherein the organic substrate is composed of a plurality of printed circuit ~~board~~ boards.

Claim 43 (currently amended): The composite laminated substrate according to claim 42, wherein the plurality of printed circuit boards are stacked, with each having ~~stacked and have separately fabricated~~ its own respective separate circuitry respectively.

Claim 44 (currently amended): The composite laminated substrate according to claim 43, wherein the organic substrate has an outer surface layer

which is a built-up surface layer, which includes a circuit, and which is made by a ~~build-up process~~ circuit.

Claim 45 (previously presented): The composite laminated substrate according to claim 37, wherein the organic substrate further comprises at least one passive component.

Claim 46 (previously presented): The composite laminated substrate according to claim 45, wherein the at least one passive component of the organic substrate is selected from the group consisting of a capacitor, an inductor, a resistor, and any mixture thereof.

Claim 47 (currently amended): The composite laminated substrate according to claim 37, wherein the organic substrate is a built-up organic substrate provided on the inorganic substrate ~~and made by a build-up process~~.

Claim 48 (previously presented): The composite laminated substrate according to claim 37, further comprising a bonding layer which is provided between the inorganic substrate and the organic substrate, and which bonds together the inorganic substrate and the organic substrate.

Claim 49 (previously presented): A composite laminated substrate for integrated and minimized electronic circuits, comprising:

an inorganic substrate having at least one passive component formed thereon or embedded therein; and

two organic substrates which are laminated to respective sides of the inorganic substrate and integrated therewith, and which have circuits for electrical connections between outer input/output ports and the at least one passive component of the inorganic substrate through the two organic substrates.

Claim 50 (previously presented): The composite laminated substrate according to claim 49, wherein the inorganic substrate is comprised of a material selected from the group consisting of ceramic, silicon and glass.

Claim 51 (currently amended): The composite laminated substrate according to claim 50, wherein the material of the inorganic substrate is ceramic and wherein the at least one passive component is one of a thick film passive component ~~made by a thick film process~~ or a thin film passive component ~~made by a thin film process~~.

Claim 52 (currently amended): The composite laminated substrate according to claim 50, wherein the material of the inorganic substrate is silicon

and wherein the at least one passive component is a semiconductor-fabricated passive component ~~made by a semiconductor fabrication process.~~

Claim 53 (previously presented): The composite laminated substrate according to claim 49, wherein the passive component is selected from the group consisting of a capacitor, an inductor and a resistor.

Claim 54 (previously presented): The composite laminated substrate according to claim 49, wherein each of the two organic substrates is composed of a plurality of printed circuit boards.

Claim 55 (currently amended): The composite laminated substrate according to claim ~~54~~ 49, wherein each of the two organic substrates is composed of a plurality of printed circuit boards which are stacked ~~respectively~~ respectively, and wherein each printed circuit board of each respective plurality of printed circuit boards has its own respective ~~separately-fabricated~~ separate circuitry.

Claim 56 (currently amended): The composite laminated substrate according to claim 55, wherein each of the two organic substrates has an outer surface layer which is a built-up surface layer, which includes a circuit, ~~and which is made by a build-up process.~~

Claim 57 (previously presented): The composite laminated substrate according to claim 49, wherein at least one of the two organic substrates further comprises at least one passive component.

Claim 58 (previously presented): The composite laminated substrate according to claim 57, wherein the at least one passive component of the at least one of the two organic substrates is selected from the group consisting of a capacitor, an inductor, a resistor, and any mixture thereof.

Claim 59 (currently amended): The composite laminated substrate according to claim 49, wherein at least one of the two organic substrates is a built-up organic substrate provided on the inorganic substrate ~~and made by a build-up process.~~

Claim 60 (currently amended): The composite laminated substrate according to claim 49, further comprising a covering layer which is provided on the inorganic substrate and covers the inorganic substrate, which integrates the inorganic substrate with one of the two organic substrates, and which comprises circuits for providing electrical connections between the at least one passive component of the inorganic substrate and said one of the two organic substrates, wherein the inorganic substrate is fully ~~embedded in~~ covered by ~~said one of the two organic substrates.~~

Claim 61 (previously presented): The composite laminated substrate according to claim 49, further comprising a bonding layer which is provided between the inorganic substrate and at least one of the two organic substrates, and which bonds together the inorganic substrate and said at least one of the two organic substrates.

Claim 62 (new): The composite laminated substrate according to claim 49, wherein the at least one passive component is separated from, so as to not directly contact, the two organic substrates.

Claim 63 (new): The composite laminated substrate according to claim 37, wherein the at least one passive component is separated from, so as to not directly contact, the organic substrate.